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March 2015

FDS8672S

N-Channel PowerTrench[®] SyncFETTM 30V, 18A, 4.8m Ω

Features

- Max $r_{DS(on)} = 4.8m\Omega$ at $V_{GS} = 10V$, $I_D = 18A$
- Max $r_{DS(on)} = 7.0 \text{m}\Omega$ at $V_{GS} = 4.5 \text{V}$, $I_D = 15 \text{A}$
- Includes SyncFET Schottky Body Diode
- High Performance Trench Technology for Extremely Low r_{DS(on)} and Fast Switching
- High Power and Current Handling Capability
- 100% R_a (Gate Resistance) Tested
- Termination is Lead-free and RoHS Compliant

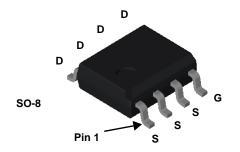


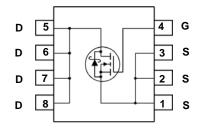
General Description

The FDS8672S is designed to replace a single MOSFET and Schottky diode in synchronous DC/DC power supplies. This 30V MOSFET is designed to maximize power conversion efficiency, providing a low $r_{\rm DS(on)}$ and low gate charge. The FDS8672S includes a patented combination of a MOSFET monolithically integrated with a Schottky diode using Fairchild's monolithic SyncFET technology.

Applications

- Synchronous Rectifier for DC/DC Converters
- Notebook Vcore Low Side Switch
- Point of Load Low Side Switch





MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted.

Symbol	Para	meter		Ratings	Units	
V_{DS}	Drain to Source Voltage			30	V	
V_{GS}	Gate to Source Voltage			±20	V	
	Drain Current -Continuous			18	^	
'D	-Pulsed		(Note 4)	80	Α	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	216	mJ	
D	Power Dissipation	$T_A = 25$ °C	(Note 1a)	2.5	W	
P_{D}	Power Dissipation	$T_A = 25$ °C	(Note 1b)	1.0	VV	
T _J , T _{STG}	Operating and Storage Junction Tempe	erature Range		-55 to +150	°C	

Thermal Characteristics

I	$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
I	$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	*C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS8672S	FDS8672S	SO8	13"	12mm	2500 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 1mA$, $V_{GS} = 0V$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 10mA, referenced to 25°C		33		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24V, V _{GS} = 0V			500	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1mA$	1.0	2.1	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 10mA, referenced to 25°C		-5		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10V, I _D = 18A		3.8	4.8	
		$V_{GS} = 4.5V, I_D = 15A$		5.3	7.0	mΩ
		$V_{GS} = 10V, I_D = 18A, T_J = 125^{\circ}C$		5.3	7.8	
9 _{FS}	Forward Transconductance	$V_{DS} = 5V, I_{D} = 18A$		78		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 15V V - 0V	2005	2670	pF
C _{oss}	Output Capacitance	$V_{DS} = 15V, V_{GS} = 0V,$ $f = 1MHz$	985	1310	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/2	135	205	pF
R_g	Gate Resistance	f = 1MHz	0.6	2.0	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			12	22	ns
t _r	Rise Time	$V_{DD} = 15V, I_{D} = 18A,$ $V_{GS} = 10V, R_{GEN} = 6\Omega$		4	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GEN} = 002$		26	42	ns
t _f	Fall Time			3	10	ns
Q_g	Total Gate Charge	V _{GS} = 0V to 10V		29	41	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } 5V$ $V_{DD} = 15$ $I_{D} = 18A$	V,	15	21	nC
Q _{gs}	Gate to Source Charge	I _D = 18A	,	5.5		nC
Q _{gd}	Gate to Drain "Miller" Charge			3.7		nC

Drain-Source Diode Characteristics

V	Source to Drain Diode Forward Voltage	V _{GS} = 0V, I _S = 18A	0.8	1.2	V
V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_S = 1.8A$	0.4	0.7	V
t _{rr}	Reverse Recovery Time	-I _E = 18A, di/dt = 300A/μs	27	43	ns
Q _{rr}	Reverse Recovery Charge	-1 F = 16A, $\frac{1}{4}$ \frac	31	50	nC
NOTES:					

^{1.} R_{0JA} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a) 50°C/W when mounted on a 1in² pad of 2 oz copper.



b) 125°C/W when mounted on a minimum pad.

^{2.} Pulse Test: Pulse Width < 300μ s, Duty cycle < 2.0%. 3. Starting T_J = 25° C, L = 3mH, I_{AS} = 12A, V_{DD} = 30V, V_{GS} = 10V. 4. Pulse current was measured at 250uS pulse, refer to Fig 11 Forward Safe Operation Area for detail.

Typical Characteristics T_J = 25°C unless otherwise noted.

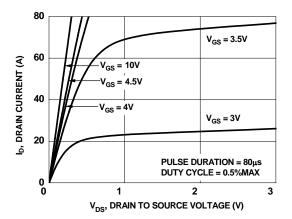


Figure 1. On-Region Characteristics

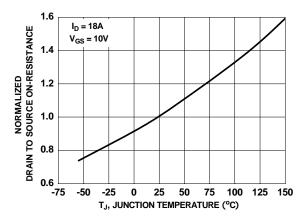


Figure 3. Normalized On-Resistance vs. Junction Temperature

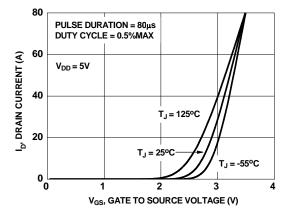


Figure 5. Transfer Characteristics

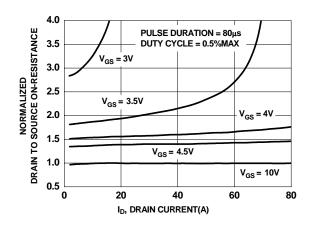


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

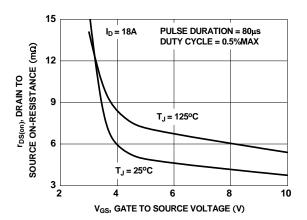


Figure 4. On-Resistance vs. Gate to Source Voltage

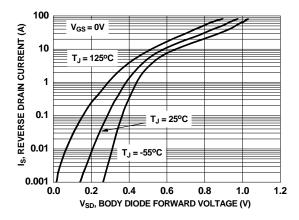


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

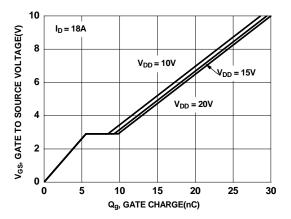


Figure 7. Gate Charge Characteristics

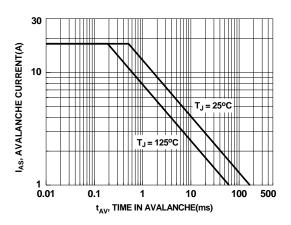


Figure 9. Unclamped Inductive Switching Capability

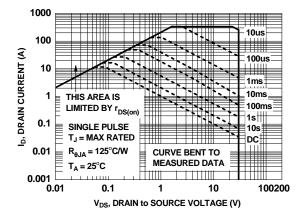


Figure 11. Forward Bias Safe Operating Area

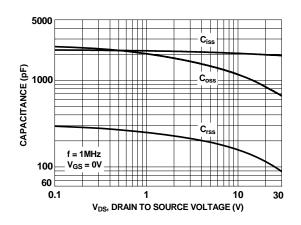


Figure 8. Capacitance vs. Drain to Source Voltage

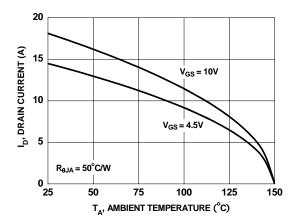


Figure 10. Maximum Continuous Drain Current vs. Ambient Temperature

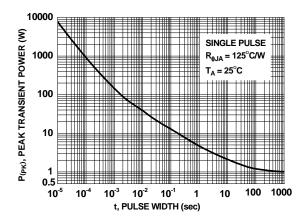


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted.

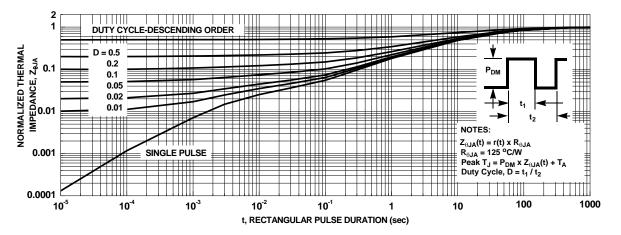


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



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